

- State-of-the-Art **EPIC-IITM** BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

description

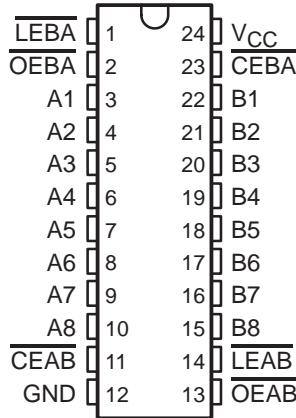
The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (\overline{LEAB} or \overline{LEBA}) and output-enable (\overline{OEAB} or \overline{OEBA}) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (\overline{CEAB}) input must be low to enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

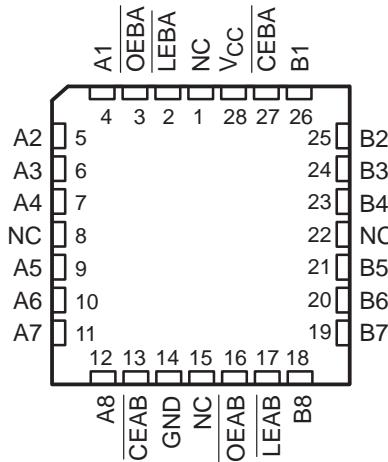
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT543A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT543A is characterized for operation from -40°C to 85°C .

SN54ABT543A . . . JT OR W PACKAGE
SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT543A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IITM is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**SN54ABT543A, SN74ABT543A
OCTAL REGISTERED TRANSCEIVERS
WITH 3-STATE OUTPUTS**

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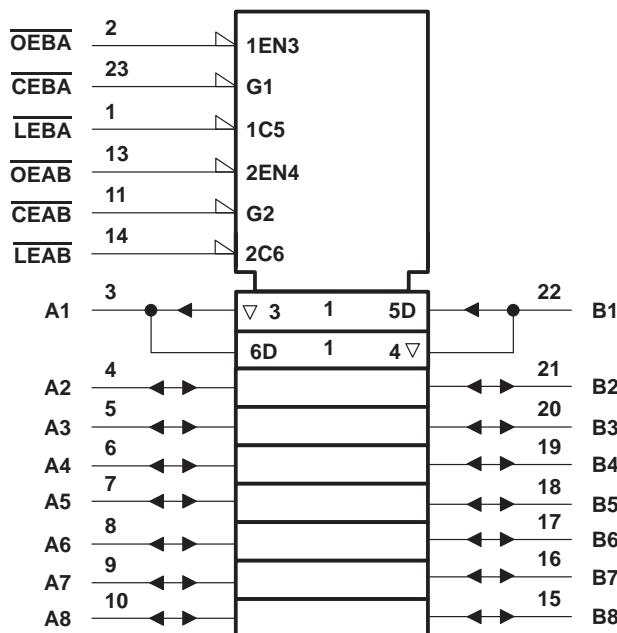
FUNCTION TABLE[†]

INPUTS				OUTPUT
CEAB	LEAB	OEAB	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B ₀ [‡]
L	L	L	L	L
L	L	L	H	H

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} .

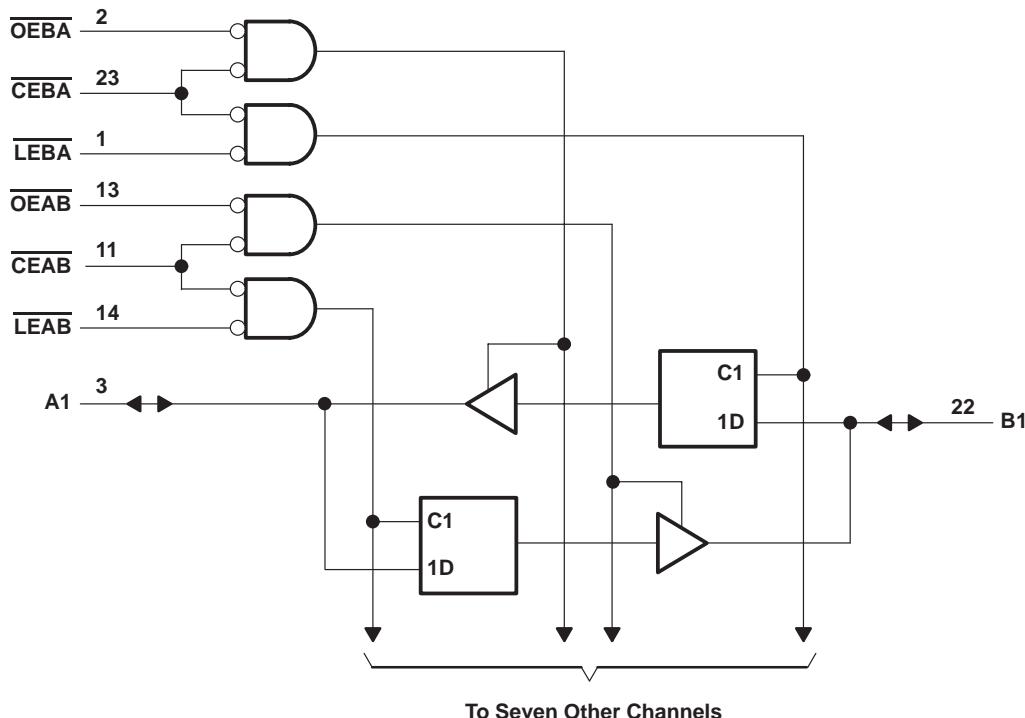
[‡] Output level before the indicated steady-state input conditions were established

logic symbol[§]



[§] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	-0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT543A	96 mA
	SN74ABT543A
	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	-18 mA
Output clamp current, I_{OK} ($V_O < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
	DW package
	81°C/W
	NT package
	67°C/W
	PW package
	120°C/W
Storage temperature range, T_{Stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

**SN54ABT543A, SN74ABT543A
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SCBS157F – JANUARY 1991 – REVISED MAY 1997

recommended operating conditions (see Note 3)

		SN54ABT543A		SN74ABT543A		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-24		-32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A = 25°C			SN54ABT543A		SN74ABT543A		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA		-1.2		-1.2		-1.2		V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -3 mA	2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = -3 mA	3			3		3		
	V _{CC} = 4.5 V I _{OH} = -24 mA	2			2				
	I _{OH} = -32 mA	2*					2		
V _{OL}	V _{CC} = 4.5 V I _{OL} = 48 mA		0.55		0.55				V
			0.55*				0.55		
V _{hys}		100							mV
I _I	Control inputs A or B ports	V _{CC} = 5.5 V, V _I = V _{CC} or GND	±1		±1		±1		µA
			±100		±100		±100		
I _{OZH} ‡	V _{CC} = 5.5 V, V _O = 2.7 V		10\$		10\$		10\$		µA
I _{OZL} ‡	V _{CC} = 5.5 V, V _O = 0.5 V		-10\$		-10\$		-10\$		µA
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V		±100				±100		µA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high		50		50		50	µA
I _{O†}	V _{CC} = 5.5 V, V _O = 2.5 V	-50* -100 -180*		-50 -200		-50 -180		mA	
I _{CC}	A or B ports	V _{CC} = 5.5 V, Outputs high	1	250*		350		250	µA
		I _O = 0, Outputs low	24	30*		34		30	mA
		V _I = V _{CC} or GND Outputs disabled	0.5	250*		350		250	µA
ΔI _{CC} ‡	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND		1.5		1.5		1.5		mA
C _i	Control inputs	V _I = 2.5 V or 0.5 V		4					pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V		7					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

\$ This data sheet limit may vary among suppliers.

¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT543A, SN74ABT543A
 OCTAL REGISTERED TRANSCEIVERS
 WITH 3-STATE OUTPUTS

SCBS157F – JANUARY 1991 – REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ABT543A		UNIT	
		$V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$			
		MIN	MAX		
t_W	Pulse duration, $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ low	3.5	3.5	ns	
t_{SU}	Setup time	High	2.5	2.5	
		Low	3	3	
	Data before $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}$ ↑	High	2.5	2.5	
		Low	3	3	
t_H	Data after $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ ↑		1	1	
	Data after $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}$ ↑		1	1	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN74ABT543A		UNIT	
		$V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$			
		MIN	MAX		
t_W	Pulse duration, $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ low	3.5	3.5	ns	
t_{SU}	Setup time	High	3.5	3.5	
		Low	3	3	
	Data before $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}$ ↑	High	3.5	3.5	
		Low	3	3	
t_H	Data after $\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$ ↑		0.5	0.5	
	Data after $\overline{\text{CEAB}}$ or $\overline{\text{CEBA}}$ ↑		0.5	0.5	

**SN54ABT543A, SN74ABT543A
OCTAL REGISTERED TRANSCEIVERS
WITH 3-STATE OUTPUTS**

SCBS157F – JANUARY 1991 – REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT543A			UNIT	
			$V_{CC} = 5 \text{ V},$ $T_A = 25^\circ\text{C}$				
			MIN	TYP	MAX		
t_{PLH}	A or B	B or A	1.6 [†]	4.4	4.4	1.6 [†] 5.5	
t_{PHL}			1.6	4.4	5.1	1.6 6.2	
t_{PLH}	\overline{LEBA} or \overline{LEAB}	A or B	1.6 [†]	4.1	5.1	1.6 [†] 6.6	
t_{PHL}			1.6	4.6	5.4	1.6 6.4	
t_{PZH}	\overline{OEBA} or \overline{OEAB}	A or B	1.4	3.9	4.1	1.4 5.1	
t_{PZL}			2	5	4.9	2 5.8	
t_{PHZ}	\overline{OEBA} or \overline{OEAB}	A or B	2.5 [†]	5.9	5.8	2.5 [†] 6.9	
t_{PLZ}			2.5 [†]	5.5	6.1	2.5 [†] 7.6	
t_{PZH}	\overline{CEBA} or \overline{CEAB}	A or B	1.4	3.9	4.7	1.4 5.6	
t_{PZL}			2	5	5.7	2 6.2	
t_{PHZ}	CEBA or CEAB	A or B	3.2 [†]	5.9	6.5	3.2 [†] 7.3	
t_{PLZ}			2.5 [†]	5.5	6.7	2.5 [†] 7.8	

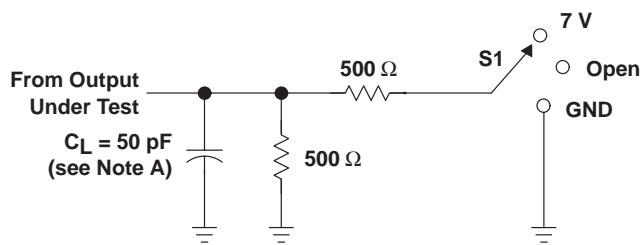
[†] This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT543A			UNIT	
			$V_{CC} = 5 \text{ V},$ $T_A = 25^\circ\text{C}$				
			MIN	TYP	MAX		
t_{PLH}	A or B	B or A	1.8 [†]	4.4	5.9	1.8 [†] 6.9	
t_{PHL}			1.9	4.4	5.9	1.9 6.9	
t_{PLH}	\overline{LEBA} or \overline{LEAB}	A or B	1.5 [†]	4.1	5.6	1.5 [†] 6.6	
t_{PHL}			2.1	4.6	6.1	2.1 7.1	
t_{PZH}	\overline{OEBA} or \overline{OEAB}	A or B	1.4	3.9	5.4	1.4 6.4	
t_{PZL}			2.5	5	6.5	2.5 7.5	
t_{PHZ}	\overline{OEBA} or \overline{OEAB}	A or B	2.5 [†]	5.9	7.4	2.5 [†] 8.4	
t_{PLZ}			2.5 [†]	5.5	7	2.5 [†] 8	
t_{PZH}	\overline{CEBA} or \overline{CEAB}	A or B	1.4	3.9	5.4	1.4 6.4	
t_{PZL}			2.5	5	6.5	2.5 7.5	
t_{PHZ}	\overline{CEBA} or \overline{CEAB}	A or B	2.9 [†]	5.9	7.4	2.9 [†] 8.4	
t_{PLZ}			2.4 [†]	5.5	7	2.4 [†] 8	

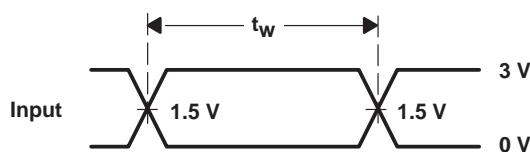
[†] This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

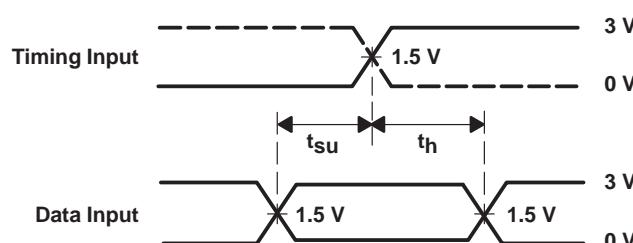


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

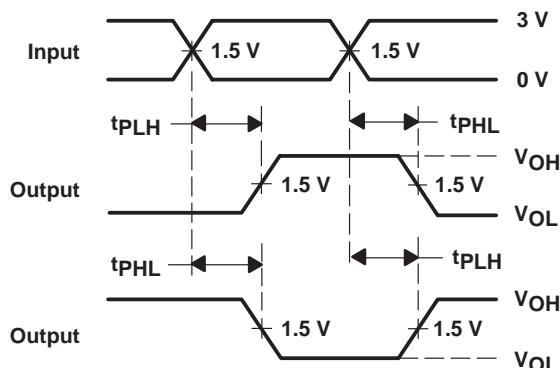
LOAD CIRCUIT



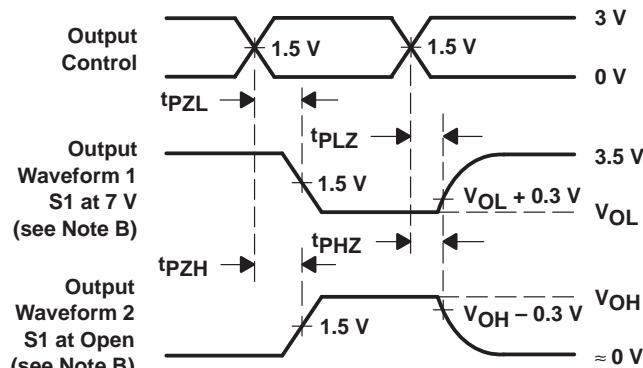
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES:

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9231402Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9231402Q3A SNJ54 ABT543AFK	Samples
5962-9231402QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231402QK A SNJ54ABT543AW	Samples
5962-9231402QLA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231402QL A SNJ54ABT543AJT	Samples
SN74ABT543ADBLE	OBsolete	SSOP	DB	24		TBD	Call TI	Call TI	-40 to 85		
SN74ABT543ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A	Samples
SN74ABT543ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A	Samples
SN74ABT543ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A	Samples
SN74ABT543ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT543ANT	Samples
SN74ABT543APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543APWLE	OBsolete	TSSOP	PW	24		TBD	Call TI	Call TI	-40 to 85		
SN74ABT543APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SNJ54ABT543AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9231402Q3A SNJ54 ABT543AFK	Samples
SNJ54ABT543AJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231402QL A SNJ54ABT543AJT	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54ABT543AW	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9231402QK A SNJ54ABT543AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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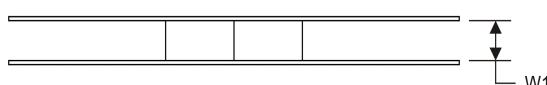
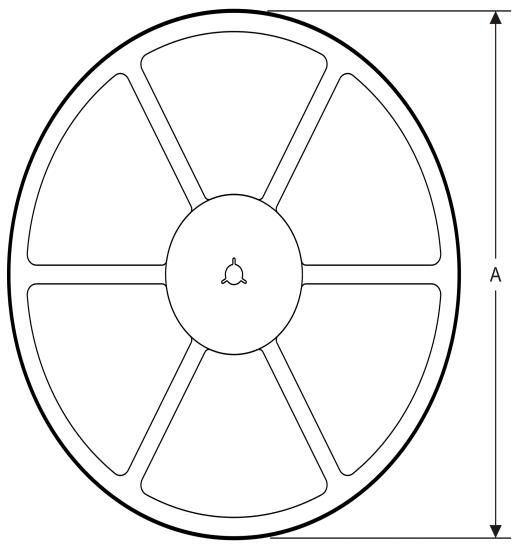
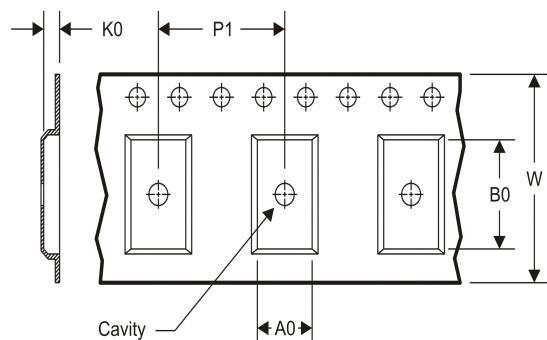
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OTHER QUALIFIED VERSIONS OF SN54ABT543A, SN74ABT543A :

- Catalog: [SN74ABT543A](#)
- Military: [SN54ABT543A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT543ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT543ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

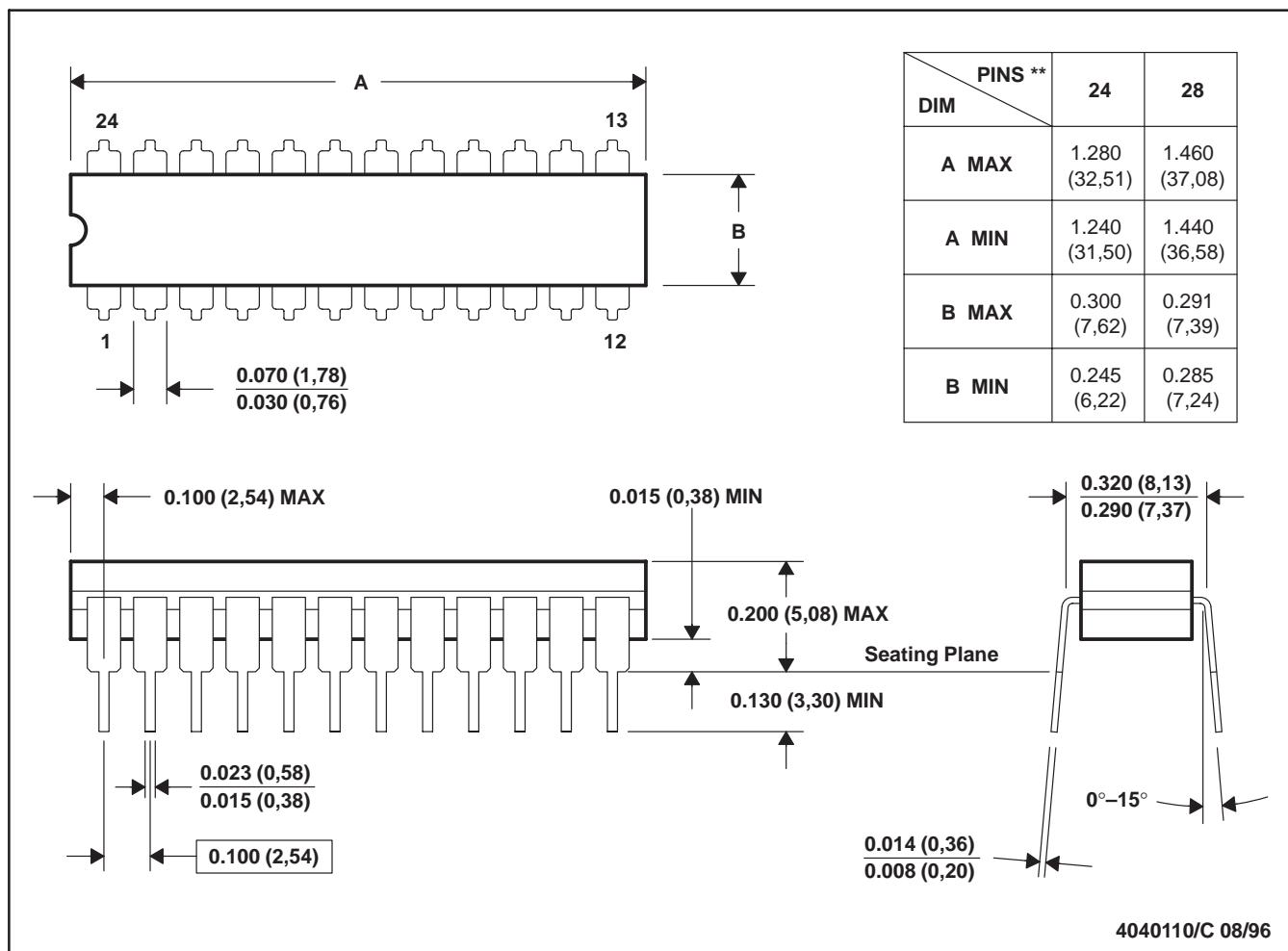

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT543ADBR	SSOP	DB	24	2000	367.0	367.0	38.0
SN74ABT543ADWR	SOIC	DW	24	2000	367.0	367.0	45.0
SN74ABT543APWR	TSSOP	PW	24	2000	367.0	367.0	38.0

JT (R-GDIP-T**)

24 LEADS SHOWN

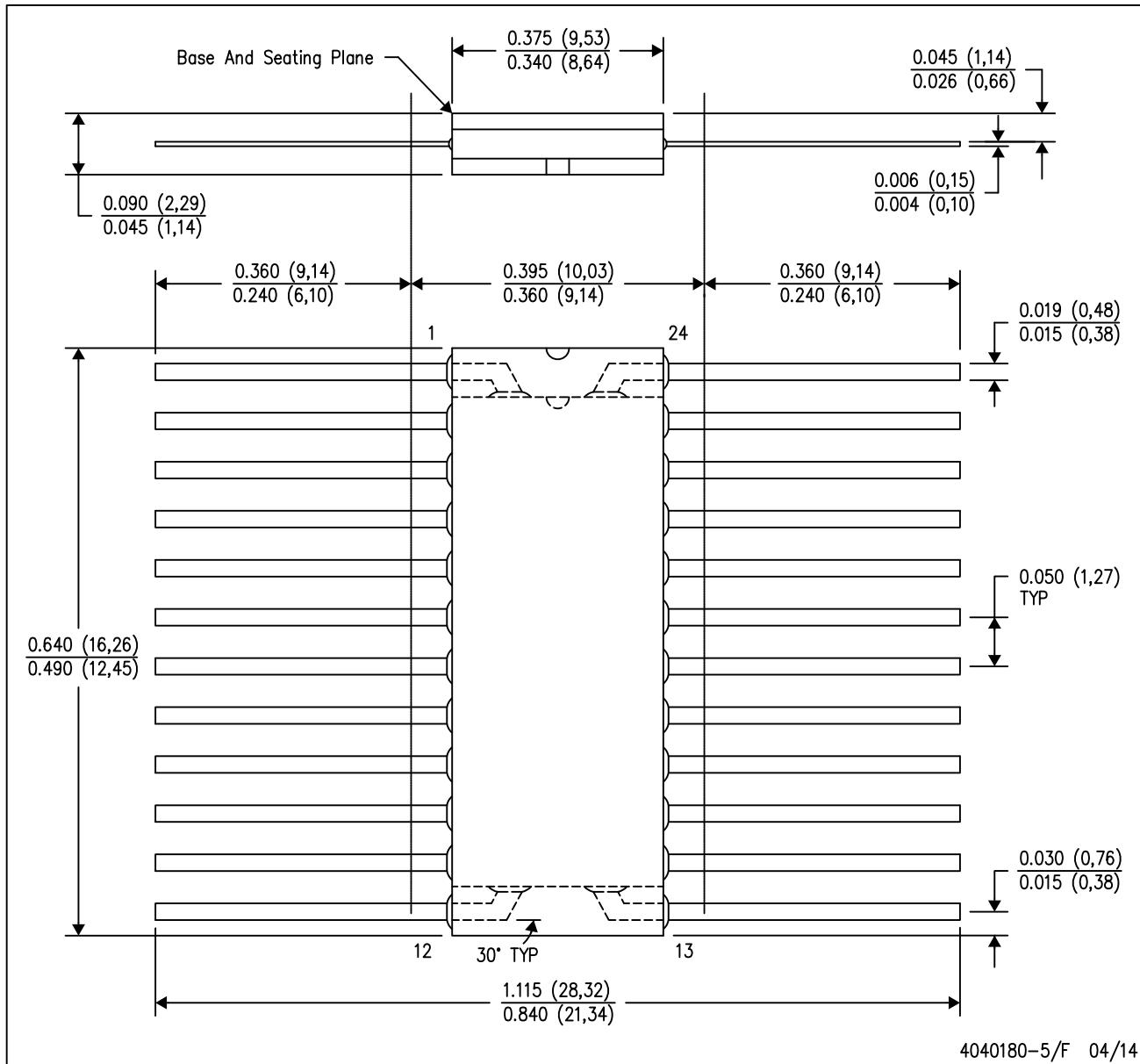
CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



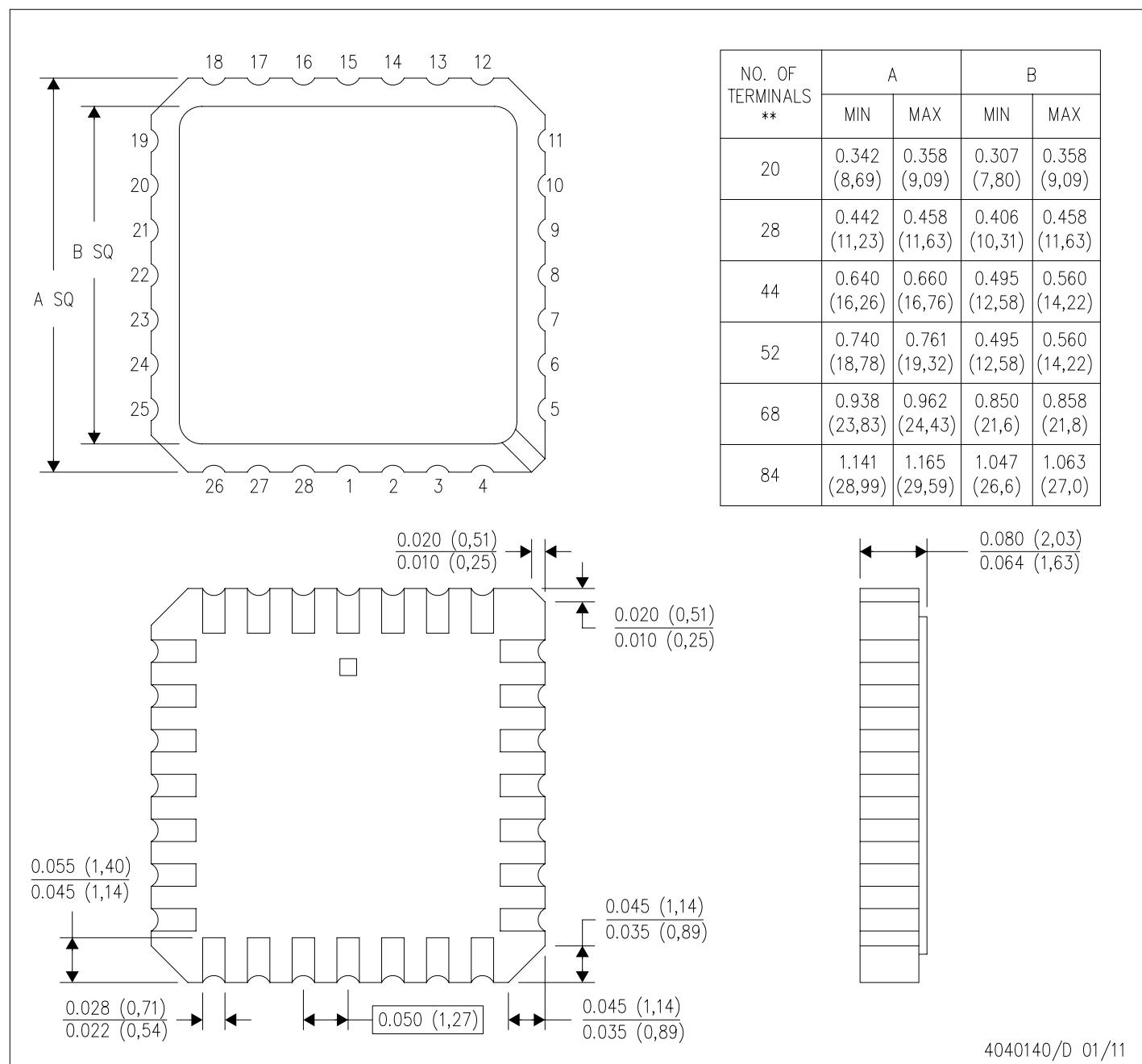
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

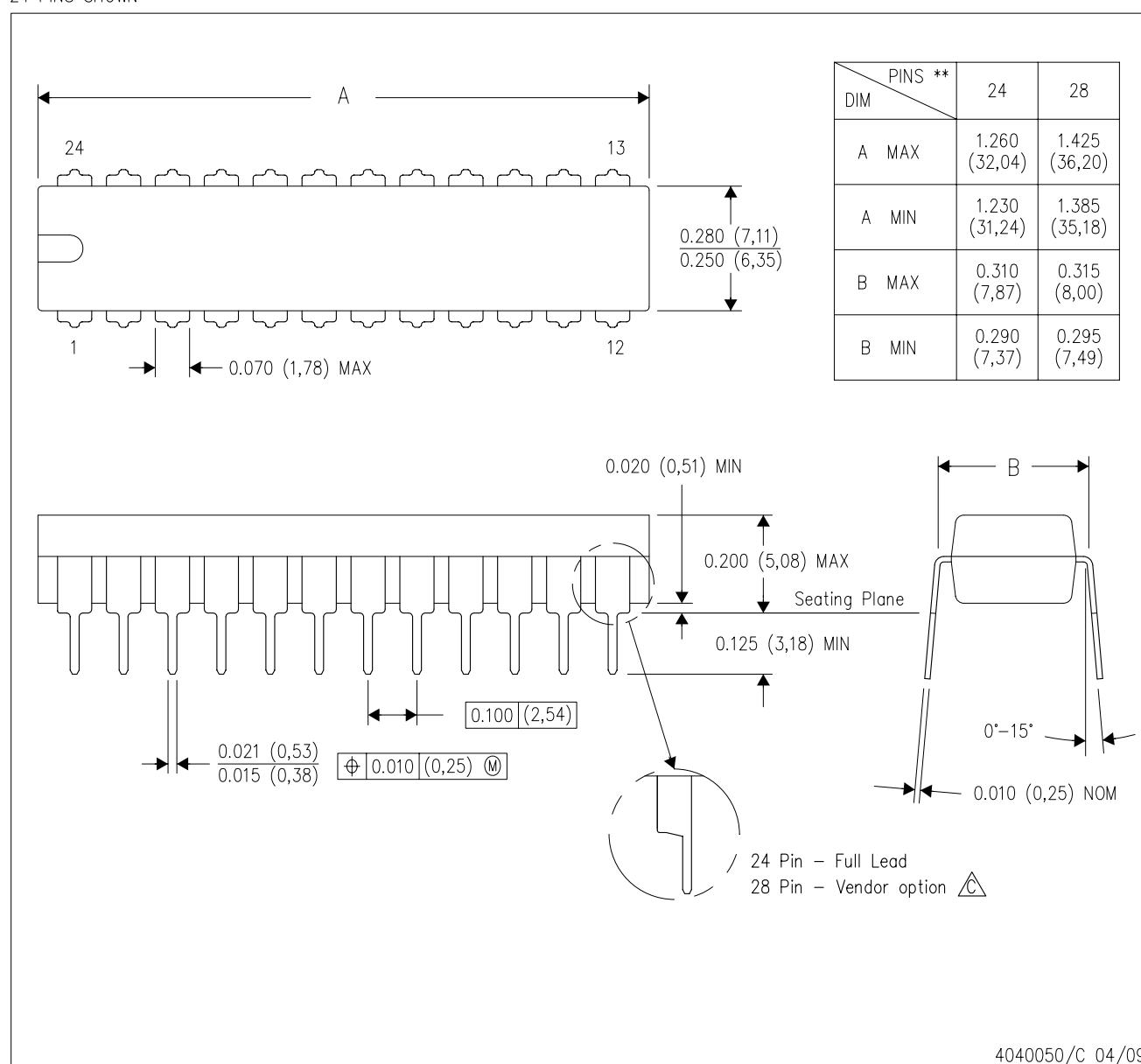
4040140/D 01/11

MECHANICAL DATA

NT (R-PDIP-T**)

24 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040050/C 04/09

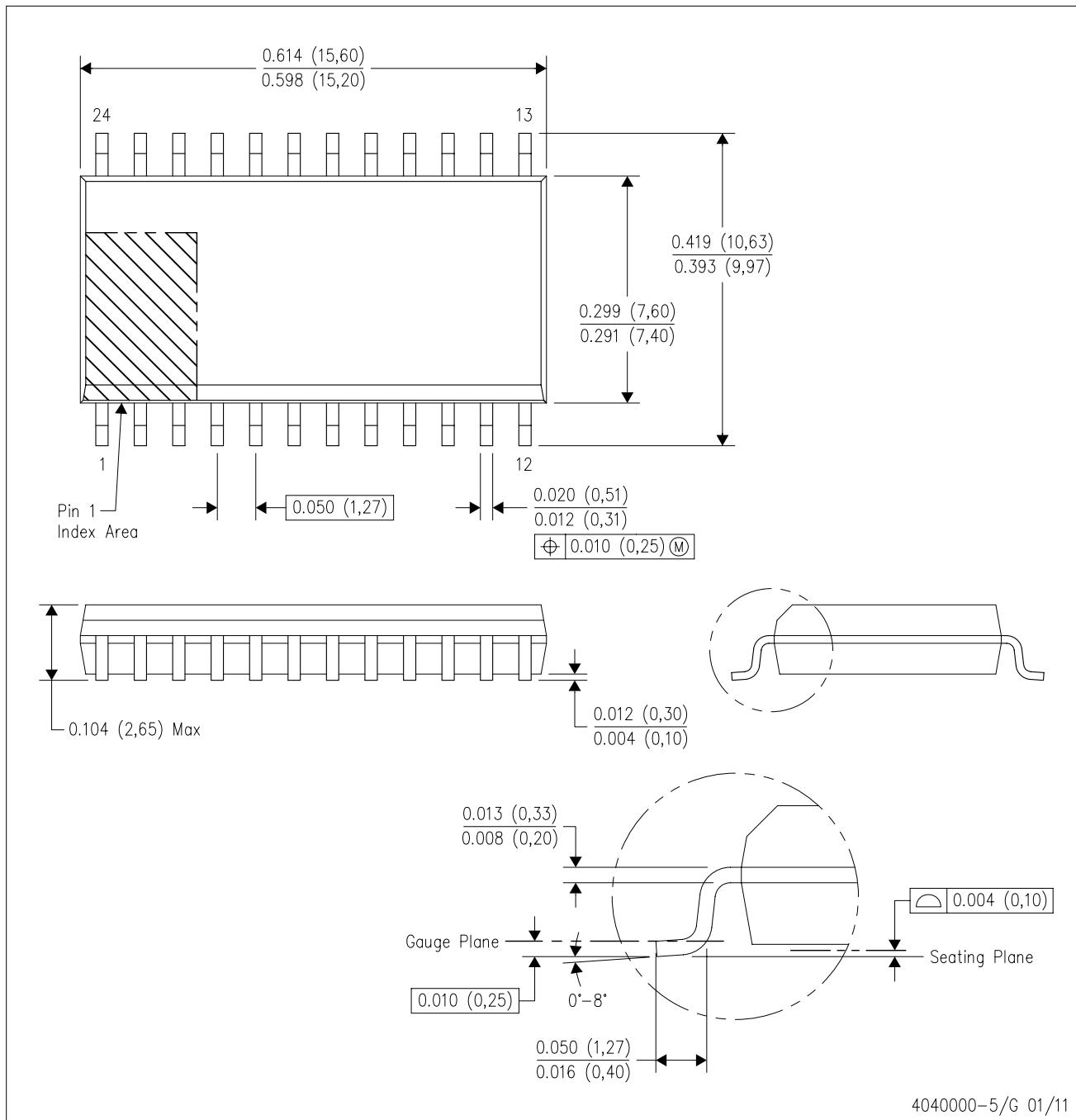
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

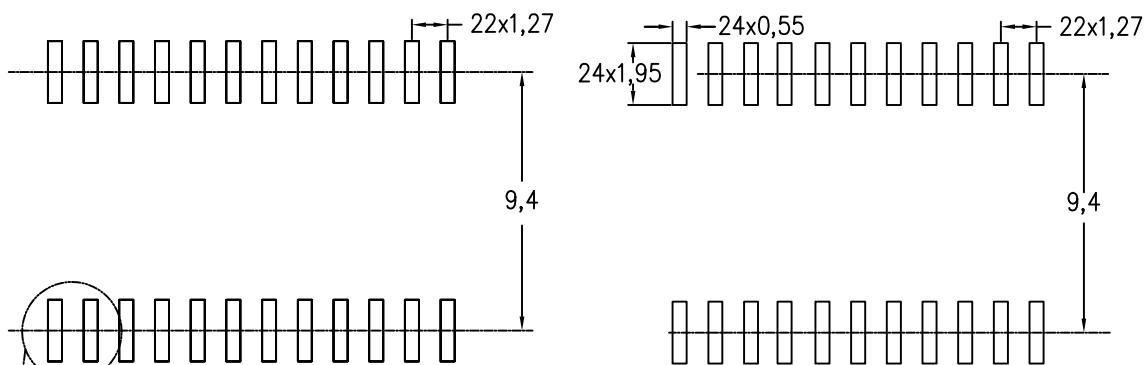


NOTES:

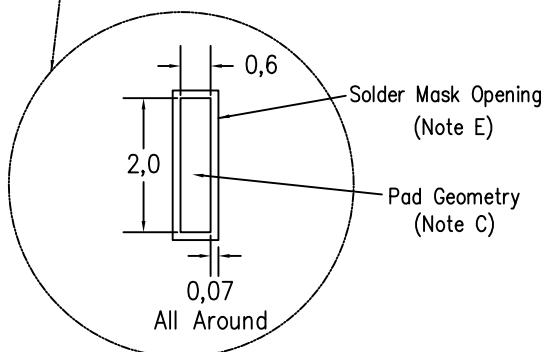
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AD.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



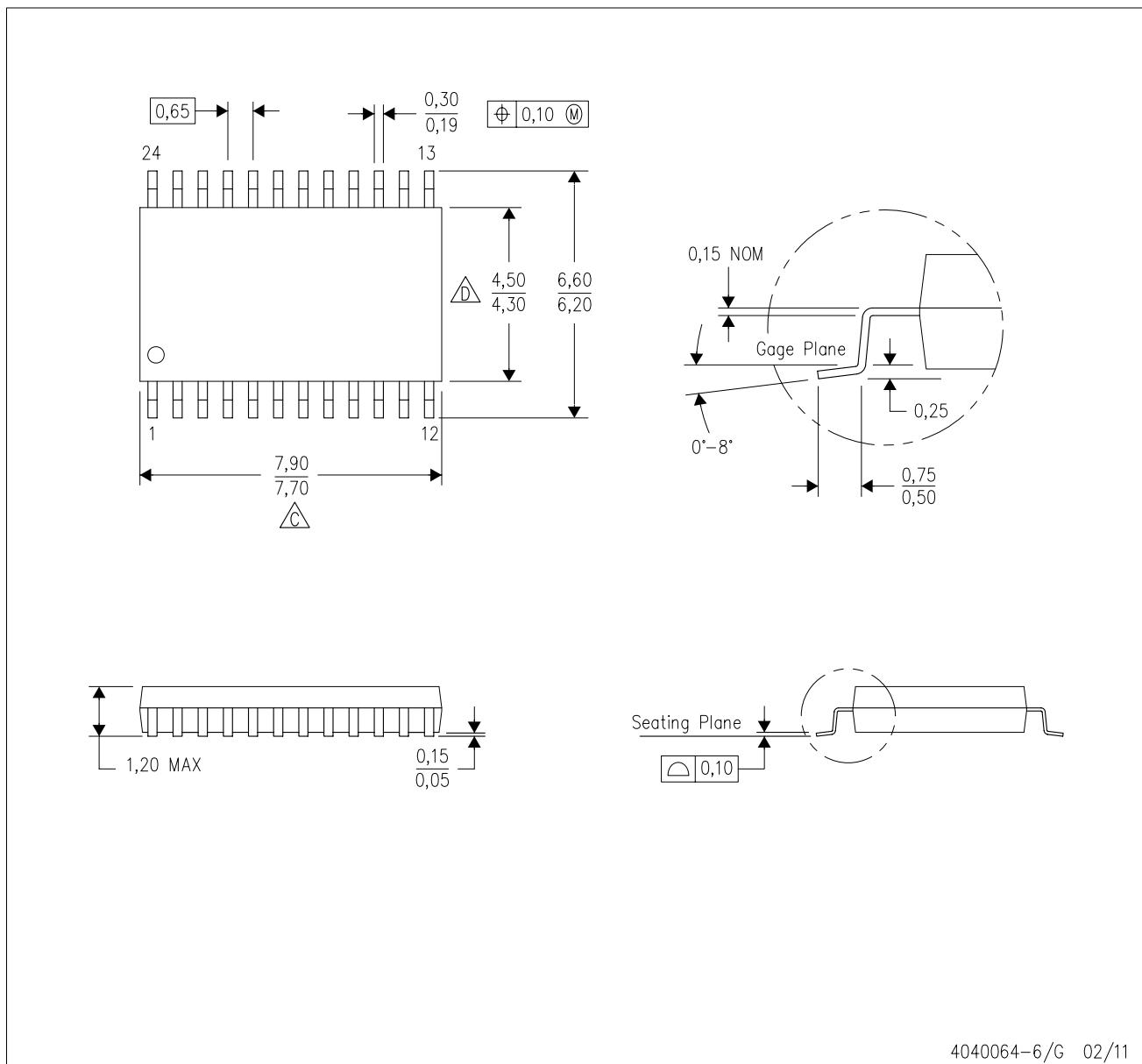
4209202-5/F 08/13

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

 D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

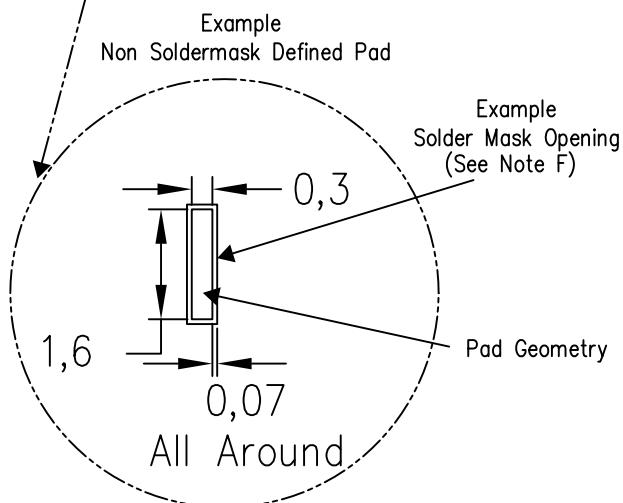
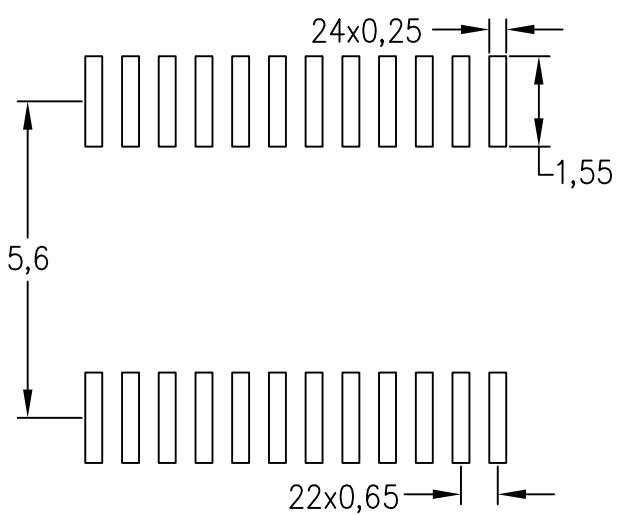
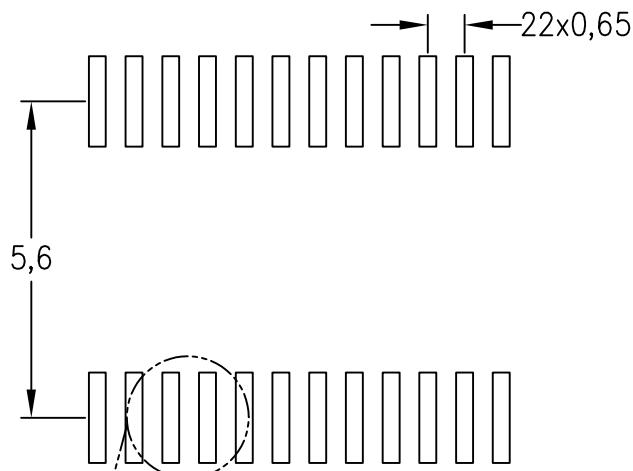
4040064-6/G 02/11

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

Example Board Layout

Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



4211284-4/F 12/12

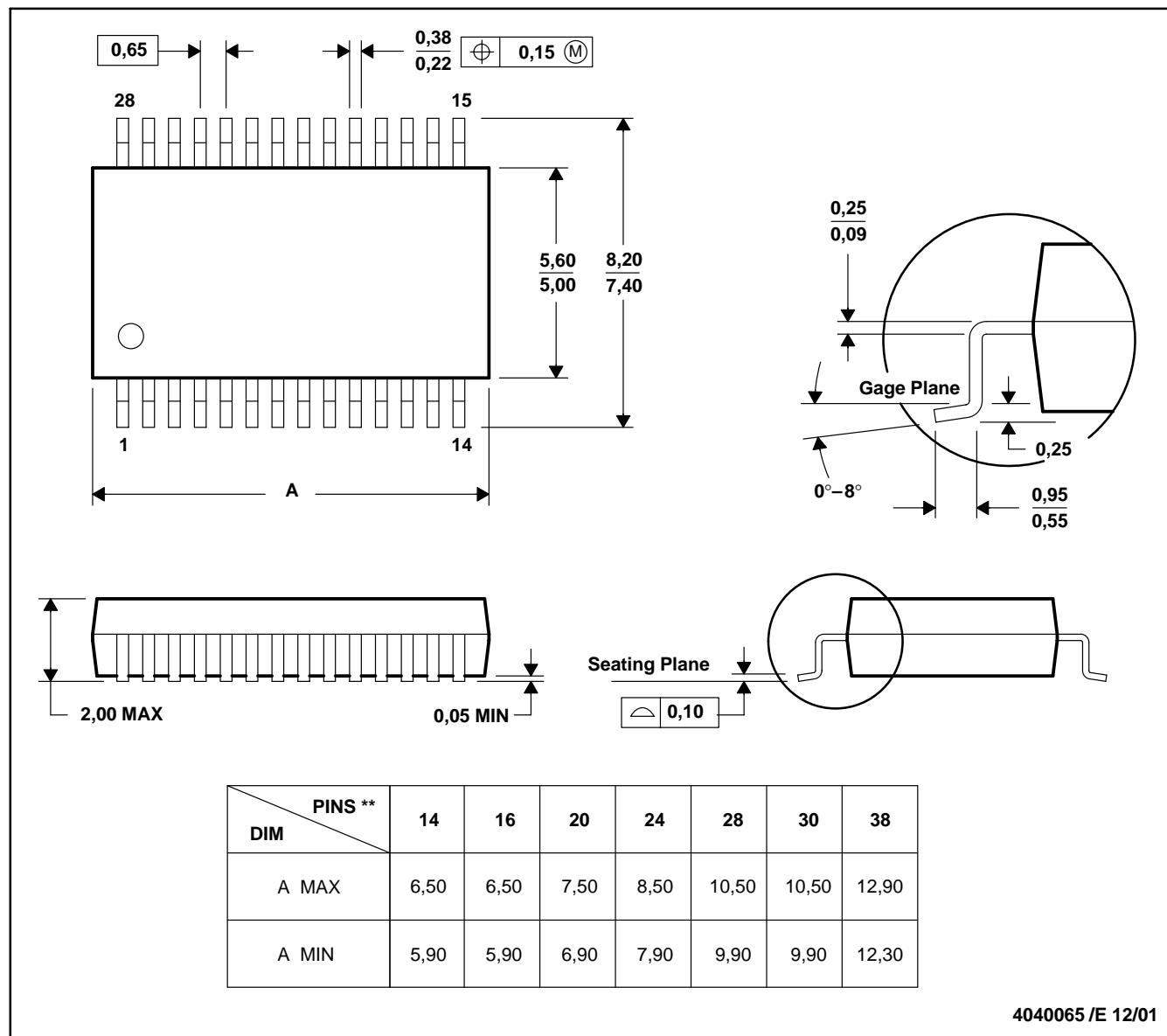
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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